

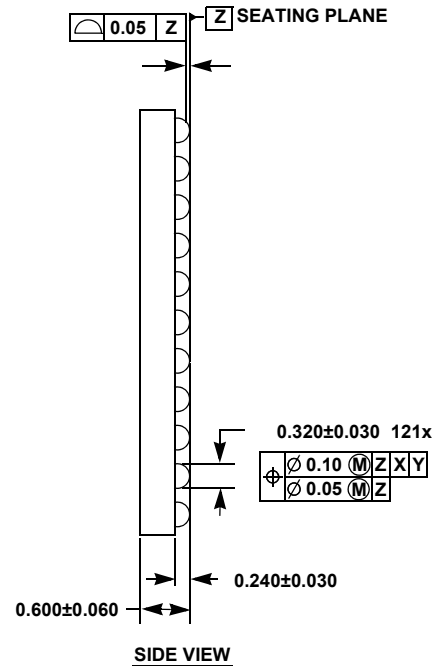
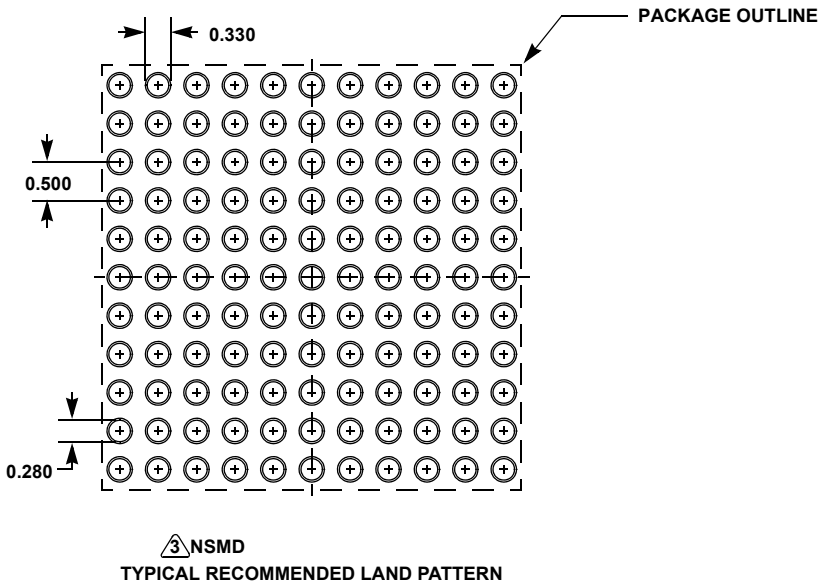
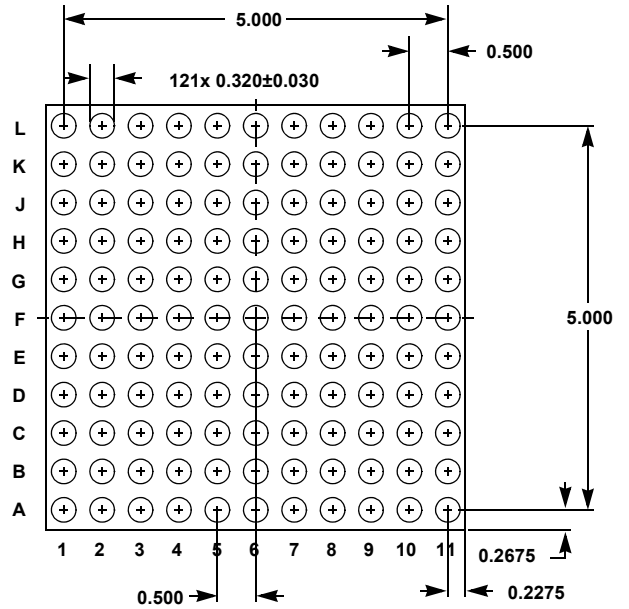
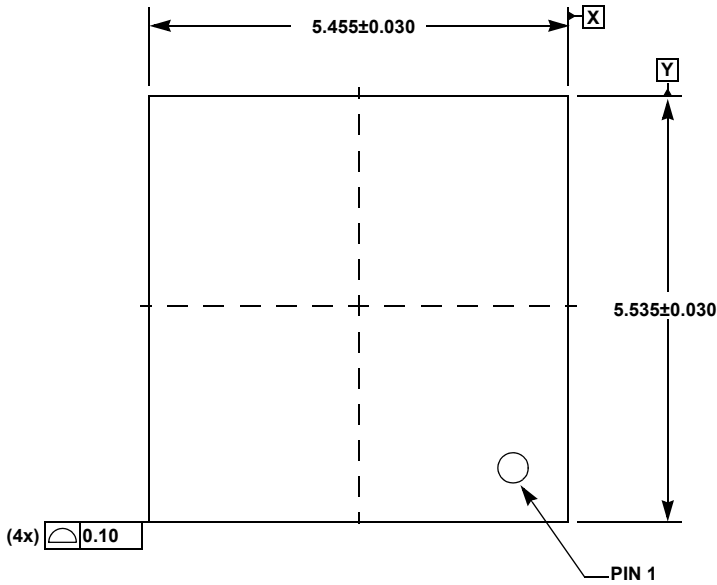
Plastic Packages for Integrated Circuits

Package Outline Drawing

W11x11.121

121 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.5mm Pitch)

Rev 2, 9/13



NOTES:

- All dimensions are in millimeters.
- Dimensions and tolerance per ASMEY 14.5M - 1994 and JESD 95-1, SPP-010.
- NSMD refers to non-solder mask defined pad design per Intersil Techbrief [TB451](#)